

A B C D E F

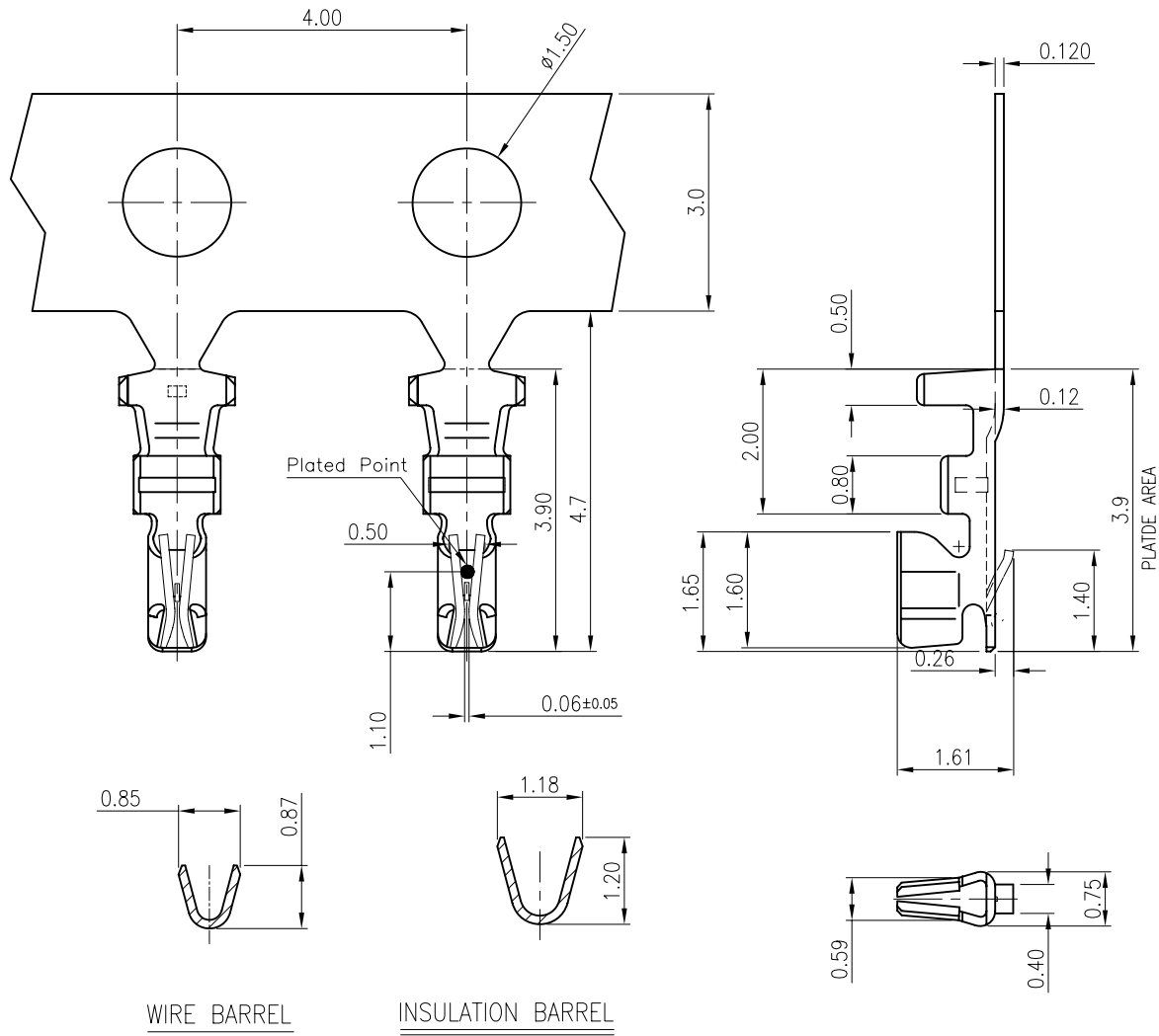
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NOTES:

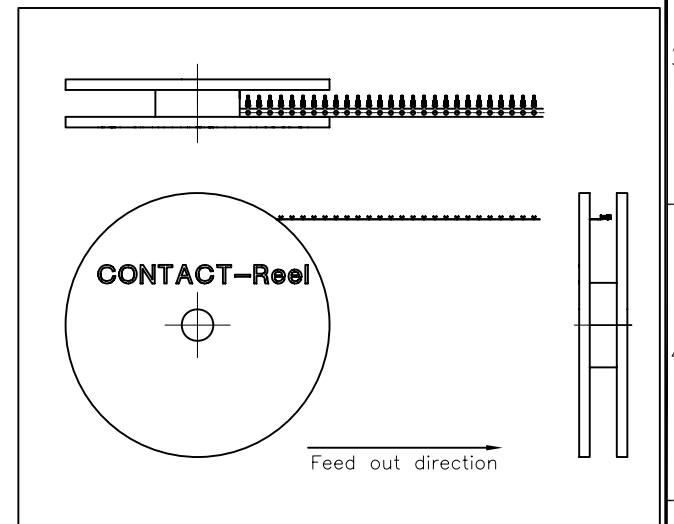
1. MATERIAL: COPPEY ALLOY
2. PLATING
 - 50~100u".Ni Under Plated OVER ALL.
 - 1:GOLD FLASH ON PLATED AREA
 - L:80~150u" PURE TIN ON PLATED AREA
 - C:15u"MIN GOLD ON PLATED AREA
3. WIRE RANGE: SUITABLE FOR
 - UL1571 AWG#32 OD=0.39±0.02mm
 - UL1571 AWG#34 OD=0.32±0.01mm
4. Current Rating:
 - AWG#32 1Amperes (per pin)
 - AWG#34 0.8Amperes (per pin)
5. CRIMPING SPEC PLS REFER TO SPEC-50211-TXXX
 - 50211-T X X X-XXX

OTHER
001: INITIAL

O: NONE

MATERIAL
1: COPPEY ALLOY

PLATING
1: GOLD FLASH
L: PURE TIN (LEAD FREE)
C: 15u"MIN GOLD
9: NONE PLATING



一般公差 TOLERANCES X ±0.5 XX ±0.15 X ±0.25 XXX ±0.1 ANGLES ±2°		宏致電子股份有限公司 Aces Electronics Co.,Ltd.	
檢驗尺寸標示 SYMBOLS INDICATE CLASSIFICATION DIMENSION		品名 (TITLE) 1.0mm WT B TERMINAL	製圖 (DR) '12/12/14 CANDY
MARK IS CRITICAL DIM. MARK IS MAJOR DIM.		圖號 (DWG NO.) 50211-TXXX-XXX	審核 (CHKD) SAM
表面處理 (FINISH)		比例 (SCALE) 1:10	單位 (UNITS) mm
			張數 (SHEET) 1 OF 1
			核准 (APPD) JASON
			SIZE REV A4 B

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